

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L3	2	438/107,109,110,112,124,126,127,612,618,617,666.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) and ("c.sub.4")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:07
L4	6	"438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) and ("c.sub.4")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:05
L5	93	"438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) and ("c4")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:06
L6	0	("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) with ("c4")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:06
L7	0	("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) same ("c4")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:06
L8	0	("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) same c4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:06
L9	0	("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) with c4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:07
L10	93	("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and c4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:09
L11	199	("257"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and c4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:07

L12	30	438/107,109,110,112,124,126, 127,612,618,617,666.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) and (c4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:09
L13	2	438/107,109,110,112,124,126, 127,612,618,617,666.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature) and (c4 adj (process or method))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:09
L14	8	("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and (c4 adj (process or method))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:21
L15	15	("257"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and (c4 adj (process or method))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:21
L16	11	("257"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and (c4 adj (process or method))	USPAT	OR	ON	2005/05/31 12:21
L17	6	("438"/\$.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)) and (c4 adj (process or method))	USPAT	OR	ON	2005/05/31 12:22
S1	1	("20040180471").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/21 14:40
S2	993	(438/107).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/23 10:50
S3	598	(438/109).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 12:41

S4	469	(438/112).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 12:41
S5	767	(438/124).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 12:41
S6	750	(438/126).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 12:41
S7	1104	(438/127).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 12:41
S8	973	(438/618).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 12:41
S9	556	(438/666).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 12:41
S10	321	(438/617).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/24 12:42
S11	342	(438/110).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/27 12:30

S12	13	semiconductor same stack\$5 same lead same (flux or reflow or encapsul\$6) same solder same ((heat adj treat\$6) or temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/27 09:59
S13	2	semiconductor with stack\$5 with lead with (flux or reflow or encapsul\$6) with solder with ((heat adj treat\$6) or temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/27 08:15
S16	2528	semiconductor and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/27 11:47
S17	343	438/107,109,110,112,124,126,127,612,618,617,666.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/05/31 12:01
S18	422	257/685,686,784,786,773,777,723.ccls. and stack\$5 and lead and (flux or reflow or encapsul\$6) and solder and ((heat adj treat\$6) or temperature)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/27 12:57
S19	1	("20040157374").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/22 12:55
S20	2	("6656840").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/27 09:48
S22	47	(anisotropic adj conduct\$5 adj adhesive) same (chip or die or ((integrated adj circuit) or ("IC"))) same (solder adj ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/27 06:42
S23	5	(anisotropic adj conduct\$5 adj adhesive) with fold\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/09/27 06:44

S24	14	(anisotropic adj conduct\$5 adj adhesive) same fold\$6	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 10:48
S26	1	("6790710").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/27 10:10
S30	5	((("5523605") or ("20040152290") or ("6683350"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/27 12:37
S31	2	("5523605").PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/27 12:33
S32	4	((("5523605") or ("20040152290"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/09/27 12:37
S36	2	((("6836006") or ("20020043708"))).PN.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/22 13:46
S38	7	(anisotropic adj conduct\$5 adj adhesive) with (semiconductor adj packag\$5)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 10:49
S39	1068	(438/107).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2004/12/23 10:50
S40	71	438/107,109,110,112,124,126,127,612,618,617,666.ccls. and (anisotropic adj conduct\$5 adj adhesive)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2004/12/23 10:52

S42	5	(("6300679") or ("6737300") or ("6635968") or ("6620652") or ("6582992")).PN.	USPAT	OR	OFF	2004/12/27 09:48
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